

# Preface

Following the great progress made in applied materials and electronics engineering, the 2014 3rd International Conference on Applied Materials and Electronics Engineering (AMEE 2014) aimed at providing a forum for presentation and discussion of state-of-the-art development in Nanoscience and Nanotechnology, Chemical and Materials Engineering, Materials Innovation and Material Technology, Construction and Materials Science, Environmental Engineering and Materials Science Electronics and Materials for Electronics, Automatic Control and Mechatronics, Information System and Computer, Communications and Networking, Building Materials, Engineering Management and other related fields. Emphasis was given to basic methodologies, scientific development and engineering applications.

This conference is co-sponsored by International Association for Scientific and High Technology and International Science and Engineering Research Center, and it is technical co-sponsored by Academy Publisher. The purpose of AMEE 2014 is to bring together researchers and practitioners from academia, industry, and government to exchange their research ideas and results in the areas of the conference.

We would like to thank all the participants and the authors for their contributions. We would also like to gratefully acknowledge the production supervisor Mr. Thomas Wohlbier, who enthusiastically supports the conference. In particular, we appreciate the full heart support of all the reviewers and staff members of the conference. We hope that AMEE 2014 will be successful and enjoyable to all participants and look forward to seeing all of you next year at the AMEE 2015.

Feb., 2014

Brendan Gan  
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